


| Product | | | | |
|-----------------|---------------|---|-----------|------------------|
| Mfr Item Number | Mfr Item Name | Version | Mfr Site | Date |
| ST25TV512-AD6G9 | CBA3*TVID0UD | A | 994I | 2018-12-09 |
| | Amount | UoM | Unit type | ST ECOPACK Grade |
| | 0.26 | mg | Each | ECOPACK® 2 |
| | Comment | ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material) | | |

| Manufacturing information | | | | |
|---------------------------|---------------------|----------------------|---------|---|
| J-STD-020 MSL Rating | Classification Temp | Nbr of Reflow Cycles | |  life.augmented |
| Not Applicable | Not Applicable | Not Applicable | | |
| bulk Solder Termination | Terminal Plating | Terminal Base Alloy | Comment | |
| Not Applicable | Not Applicable | N/A | | |

| Package Designator | Size | Nbr of instances | Shape | |
|--------------------|--|------------------|---------|--|
| CHP | 0.954x0.853x0.120 | 4 | No lead | |
| Comment | Package : A3 GOLD BUMPED DICE DM00249510 | | | |

| QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015 | |
|--|-------------|
| Query | Response |
| 1 - Product(s) meets EU RoHS requirement without any exemptions | TRUE |
| 2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply) | FALSE |
| 3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s) | FALSE |
| 4 - Product(s) does not meet EU RoHS requirements and is not under exemptions | FALSE |
| Exemption Id. | Description |
| | |

| QueryList : REACH-27th June 2018 | | | | |
|--|-------------------------|------------------------|-------------|----------------|
| Query | | | | Response |
| 1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH | | | | TRUE |
| CategoryLevel_Name | CategoryLevel_Threshold | amount in product (mg) | Application | ppm in product |
| | | | | |

| Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document | | | | | | Mfr Item Name | CBA3*TVID0UD | | | | 2000000.0 | 996104.0 |
|--|---------------------------------|-------|-----|----------|--------------------|-----------------|--------------|--------|-------|-----|---|--------------------------------|
| Homogeneous Material | Material Group | Mass | UoM | Level | Substance Category | Substance | CAS | Exempt | Mass | UoM | Concentration in homogeneous material (ppm) | Concentration in product (ppm) |
| Die or dies | M-011 Other inorganic materials | 0.247 | mg | supplier | die | Silicon (Si) | 7440-21-3 | | 0.227 | mg | 919028 | 888802 |
| | | | | supplier | metallization | Aluminium (Al) | 7429-90-5 | | 0.002 | mg | 8097 | 7831 |
| | | | | supplier | Passivation | Silicon Nitride | 12033-89-5 | | 0.001 | mg | 4049 | 3915 |
| | | | | supplier | Passivation | Silicon Oxide | 7631-86-9 | | 0.017 | mg | 68826 | 66562 |
| Bump | M-011 Other inorganic materials | 0.007 | mg | supplier | Bump metalization | Gold (Au) | 7440-57-5 | | 0.007 | mg | 1000000 | 28994 |